

Serial No.: 09/965,234

- 25. (Amended) A surface mount light emitting diode package, comprising:
a housing;
a plurality of light emitting diode die supported by the housing; and
a plurality of electrical contacts on the outside of the housing, said
contacts adapted for surface mounting to a circuit board and providing electrical signals
to said plurality of light emitting diode die,
wherein the plurality of die comprise integrally connected adjacent die
from a single wafer. --

Please add the following new claims:

- 29. (New) The surface mount light emitting diode package as recited in
claim 21, further comprising a reinforcing pin integrally formed on the outside of the
integrated circuit substrate.
30. (New) The surface mount light emitting diode package as recited in
claim 29, wherein one of said plurality of electrical contacts comprises a cathode contact
and wherein another of said plurality of electrical contacts comprises an anode contact,
and wherein the reinforcing pin comprises a non-electrode reinforcing pin positioned
between the cathode contact and the anode contact.
31. (New) The surface mount light emitting diode package as recited in
claim 25, further comprising a reinforcing pin formed on the integrally connected
adjacent die. --